

Global High Thermal Conductivity Thermal Interface Materials for AI Chips Market Growth 2026-2032

<https://marketpublishers.com/r/GF9E50BD8726EN.html>

Date: October 2026

Pages: 128

Price: US\$ 3,660.00 (Single User License)

ID: GF9E50BD8726EN

Abstracts

The global High Thermal Conductivity Thermal Interface Materials for AI Chips market size is predicted to grow from US\$ 959 million in 2025 to US\$ 2445 million in 2032; it is expected to grow at a CAGR of 14.3% from 2026 to 2032.

High thermal conductivity thermal interface materials for AI chips fill microscopic gaps between the die, package lid, cold plate and heat sink, reducing contact resistance and transferring very high heat flux into the cooling system. Products include metal foils, liquid metals, gels, greases, phase-change materials, pads and graphite composites and must balance high conductivity, low interface resistance, conformability, pump-out stability, electrical insulation and long-term reliability. In 2025, global High Thermal Conductivity Thermal Interface Materials for AI Chips production reached approximately 28.0 K MT.

Rapidly rising AI-accelerator power and package heat flux are expanding liquid cooling from premium servers into broader data-center deployment, increasing demand for high-performance materials at TIM1, TIM1.5 and cold-plate interfaces. Tight integration of HBM and GPUs also raises the importance of local temperature gradients and warpage control.

Conventional greases and pads are upgrading toward highly filled gels, phase-change materials, indium-based metals and liquid metals. Bulk thermal conductivity is not the only performance metric; wetting, bond-line thickness, assembly pressure, thermal cycling and pump-out reliability determine actual interface resistance.

Suppliers must qualify materials jointly with package houses, server OEMs, cold-plate manufacturers and liquid-cooling system providers. Fast AI-chip design cycles and high

customization favor companies that can offer multiple material formats, automated dispensing compatibility and extensive reliability data.

Report Scope

LP Information, Inc. (LPI) ' newest research report, the “High Thermal Conductivity Thermal Interface Materials for AI Chips Industry Forecast” looks at past sales and reviews total world High Thermal Conductivity Thermal Interface Materials for AI Chips sales in 2025, providing a comprehensive analysis by region and market sector of projected High Thermal Conductivity Thermal Interface Materials for AI Chips sales for 2026 through 2032. With High Thermal Conductivity Thermal Interface Materials for AI Chips sales broken down by region, market sector and sub-sector, this report provides a detailed analysis in US\$ millions of the world High Thermal Conductivity Thermal Interface Materials for AI Chips industry.

This Insight Report provides a comprehensive analysis of the global High Thermal Conductivity Thermal Interface Materials for AI Chips landscape and highlights key trends related to product segmentation, company formation, revenue, and market share, latest development, and M&A activity. This report also analyzes the strategies of leading global companies with a focus on High Thermal Conductivity Thermal Interface Materials for AI Chips portfolios and capabilities, market entry strategies, market positions, and geographic footprints, to better understand these firms' unique position in an accelerating global High Thermal Conductivity Thermal Interface Materials for AI Chips market.

This Insight Report evaluates the key market trends, drivers, and affecting factors shaping the global outlook for High Thermal Conductivity Thermal Interface Materials for AI Chips and breaks down the forecast by Type, by Application, geography, and market size to highlight emerging pockets of opportunity. With a transparent methodology based on hundreds of bottom-up qualitative and quantitative market inputs, this study forecast offers a highly nuanced view of the current state and future trajectory in the global High Thermal Conductivity Thermal Interface Materials for AI Chips.

This report presents a comprehensive overview, market shares, and growth opportunities of High Thermal Conductivity Thermal Interface Materials for AI Chips market by product type, application, key manufacturers and key regions and countries.

Segmentation by Type:

Metal-Based TIM

Silicone Polymer TIM

Non-Silicone Polymer TIM

Graphite and Carbon TIM

Phase-Change TIM

Other

Segmentation by Product Form:

Thermal Paste and Grease

Gap Pad

Thermal Gel

Film and Foil

Liquid Metal

Other

Segmentation by Thermal Conductivity:

5 to 10 W per Meter-Kelvin

10 to 20 W per Meter-Kelvin

20 to 50 W per Meter-Kelvin

Above 50 W per Meter-Kelvin

Segmentation by Application:

AI GPUs and Accelerators

HBM Stacks

High-Performance CPUs

Network Switch ASICs

Optical Transceivers

Other

This report also splits the market by region:

Americas

United States

Canada

Mexico

Brazil

APAC

China

Japan

Korea

Southeast Asia

India

Australia

Europe

Germany

France

UK

Italy

Russia

Middle East & Africa

Egypt

South Africa

Israel

Turkey

GCC Countries

The below companies that are profiled have been selected based on inputs gathered from primary experts and analysing the company's coverage, product portfolio, its market penetration.

Indium

Henkel

Parker Chomerics

Laird Performance Materials

Shin-Etsu Chemical

Dow

DuPont

Resonac

Fujipoly

Honeywell

Boyd

3M

Momentive

Shenzhen FRD Science & Technology

Jones Tech

Tanyuan Technology

Guangdong Suqun New Material

Key Questions Addressed in this Report

What is the 10-year outlook for the global High Thermal Conductivity Thermal Interface Materials for AI Chips market?

What factors are driving High Thermal Conductivity Thermal Interface Materials for AI Chips market growth, globally and by region?

Which technologies are poised for the fastest growth by market and region?

How do High Thermal Conductivity Thermal Interface Materials for AI Chips market opportunities vary by end market size?

How does High Thermal Conductivity Thermal Interface Materials for AI Chips break out by Type, by Application?

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